

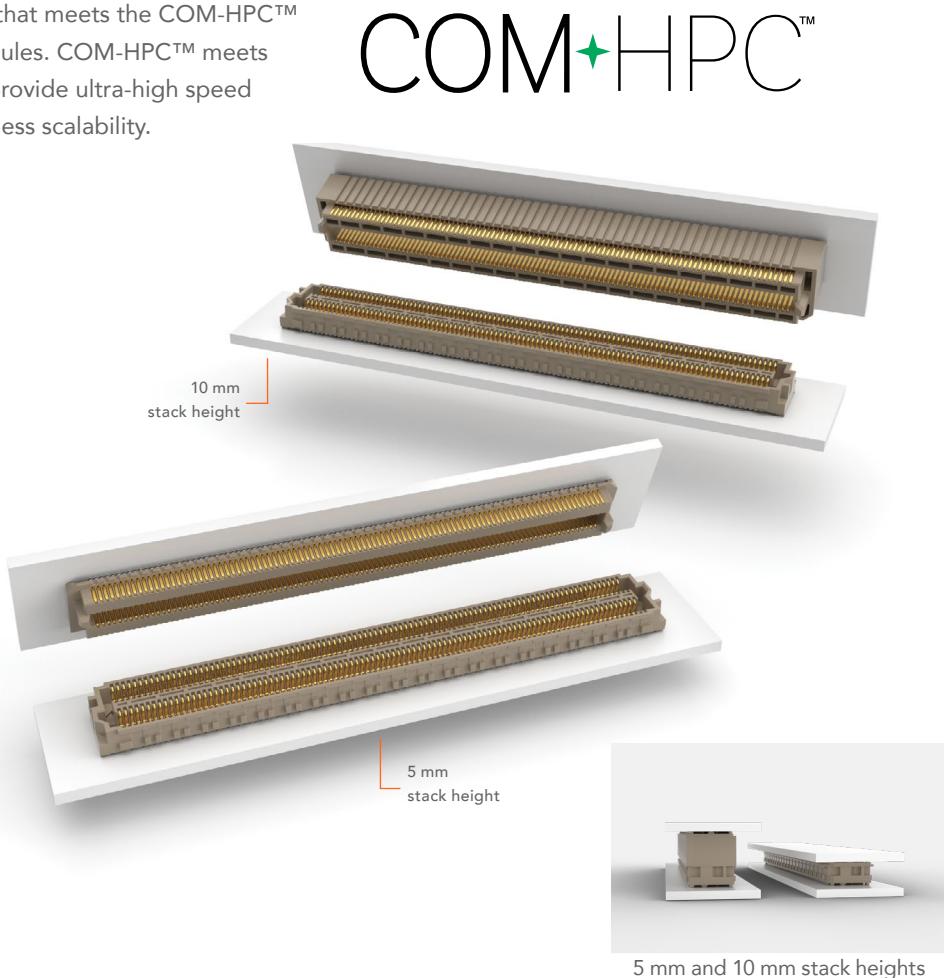
COM-HPC™ INTERCONNECT SOLUTIONS

0.635 mm PITCH HIGH-SPEED, HIGH-DENSITY SYSTEM

Samtec offers a high-density interconnect system that meets the COM-HPC™ standard for high-performance Computer-on-Modules. COM-HPCTM meets the growing demands for embedded systems to provide ultra-high speed performance and extended connectivity with limitless scalability.

HIGH-SPEED PERFORMANCE

- Up to 32 Gbps per channel
 - 4096 Gbps max aggregate
 - 2088 Gbps per square inch
- PCIe® Gen 4/5 compliant
- 10 G/25 G Ethernet compliant
- Up to 300 W at 11.4 – 12.6 Volts



5 mm and 10 mm stack heights

HIGH-DENSITY DESIGN

- High pin count interconnect system
 - 400 total pins
 - 4 x 100 design
- 0.635 mm pitch
 - Row 1 to row 2: 2.2 mm
 - Row 2 to row 3: 2.4 mm
 - Row 3 to row 4: 2.2 mm

APPLICATIONS

- Datacom & Telecom
- Embedded Edge Servers
- Industrial
- Medical Imaging
- 5G Wireless Infrastructure
- 5G Connected Vehicles



System

- **ASP-209946-01 (Female) / ASP-214802-01 (Male) – 5 mm Stack Height COM-HPC™ Interconnects**
- **ASP-209946-01 (Female) / ASP-209948-01 (Male) – 10 mm Stack Height COM-HPC™ Interconnects**

For more information, please contact standards@samtec.com